

POLISHING APPARATUS AND METHOD FOR FORMING AN INTEGRATED CIRCUIT

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Abstract of the Disclosure

10 In one embodiment, a semiconductor substrate (38) is
uniformly polished using a polishing pad (16) that has a first
polishing region (26), a second polishing region (28), and a third
polishing region (30). The semiconductor substrate (38) is aligned to
the polishing pad (16), such that the center of the semiconductor
substrate (38) overlies the second polishing region (28), and the edge
of the semiconductor substrate overlies the first polishing region (26)
and the third polishing region (30). During polishing, the
15 semiconductor substrate (38) is not radially oscillated over the
surface of the polishing pad, and as a result a more uniform
polishing rate is achieved across the semiconductor substrate (38).
This allows the semiconductor substrate (38) to be uniformly polished
from center to edge, and increases die yield because die located on
20 the semiconductor substrate (38) are not over polished.